

Features

- Glass passivated superfast recovery rectifiers
- Ideal for automated placement
- High temperature soldering 250°C/10seconds at terminals
- Plastic material used carries underwriters laboratory classification 94V-0



DO-214AC (SMA)

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1J	ES1K	ES1M	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	105	140	210	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	150	200	300	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	F.0									A
Peak Forward Surge Current 8.3 ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}	H0									A
Operating Junction Temperature Range	T_J	-55 to +150									°C
Storage Temperature Range	T_{STG}	-55 to +150									°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	ES1A	ES1B	ES1C	ES1D	ES1F	ES1G	ES1J	ES1K	ES1M	Unit								
Maximum Instantaneous Forward Voltage @F.0A	V_F	0.95				1.3		1.7			V								
Typical Junction Capacitance ^F	C_J	F€				I					pF								
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R ($T_A=25^\circ\text{C}$)	5.0									uA								
	I_R ($T_A=100^\circ\text{C}$)	100									uA								
Typical Reverse Recovery Time ^G	t_{rr}	35									nS								
Typical Thermal Resistance Junction to Ambient ³	$R_{\theta JA}$	85									°C/W								
Typical Thermal Resistance Junction to Lead ³	$R_{\theta JL}$	35									°C/W								

Note:

1. Measured at 1 MHz and Applied $V_R=4.0$ Volts
2. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$
3. P.C.B. Mounted on 0.2 x 0.2" (5.0 x 5.0mm) Copper Pad Area.

Typical Characteristics Curves

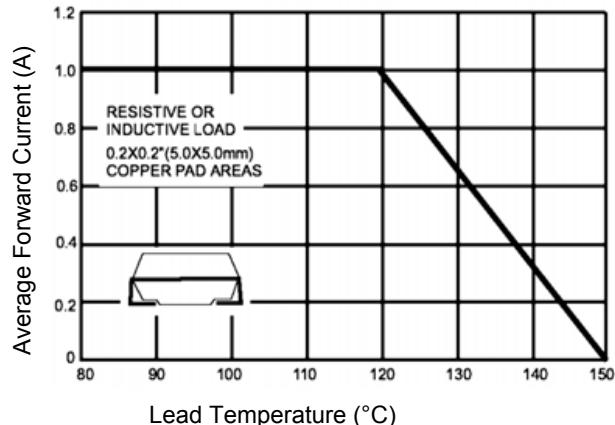


Figure 1. Forward Current Derating Curve

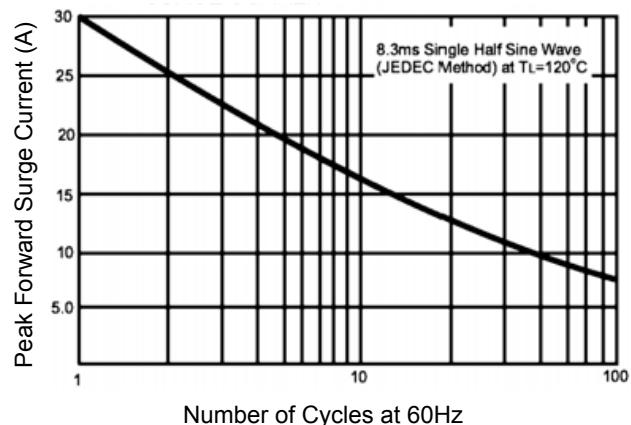


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

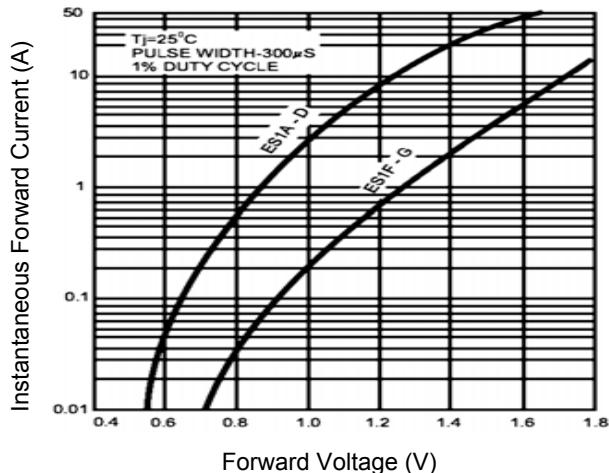


Figure 3. Typical Instantaneous Forward Characteristics

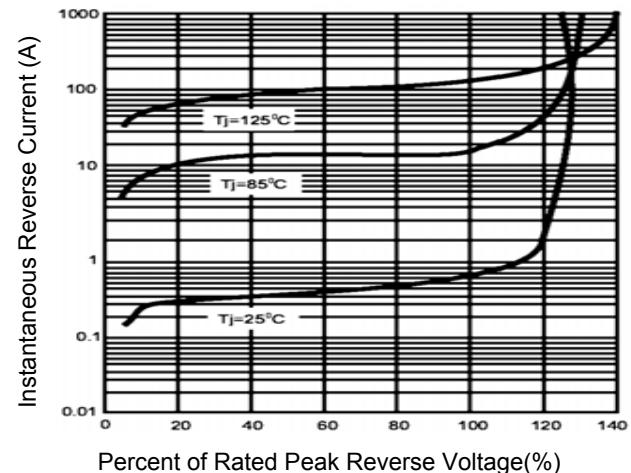


Figure 4. Typical Reverse Characteristics

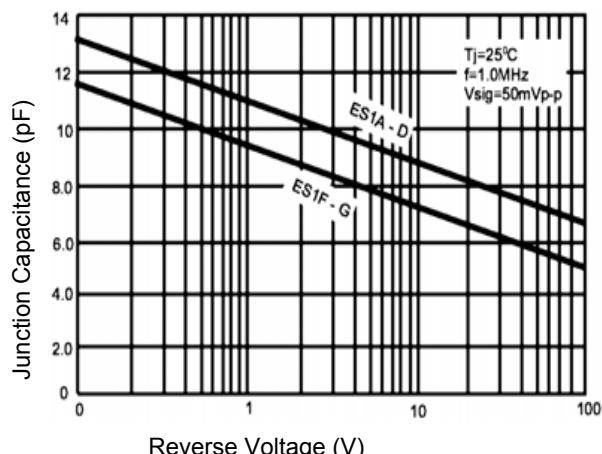
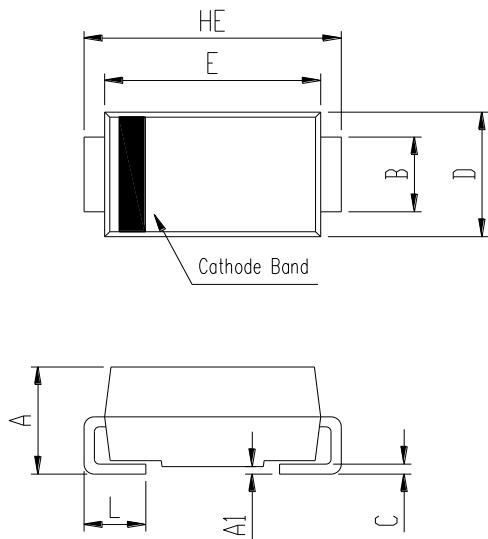


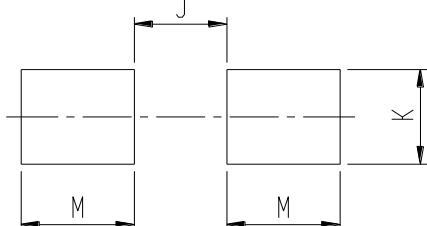
Figure 5. Typical Junction Capacitance

Package Outline Dimensions DO-214AC (SMA)



SMA (DO-214AC)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.90	2.25	0.075	0.089
A1	0.00	0.20	0.000	0.008
B	1.27	1.63	0.050	0.064
C	0.15	0.31	0.006	0.012
D	2.40	2.65	0.094	0.104
E	4.00	4.60	0.157	0.181
HE	4.80	5.20	0.189	0.205
L	0.80	1.50	0.031	0.059

Recommended Pad Layout



Recommended Pad Layout (Reference ONLY)				
DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	-	2.20	-	0.087
K	1.72	-	0.068	-
M	2.00	-	0.079	-